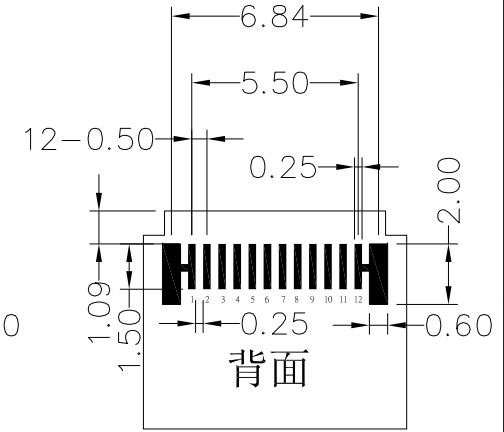
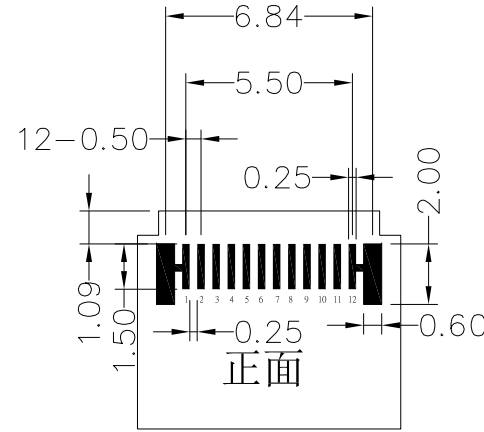
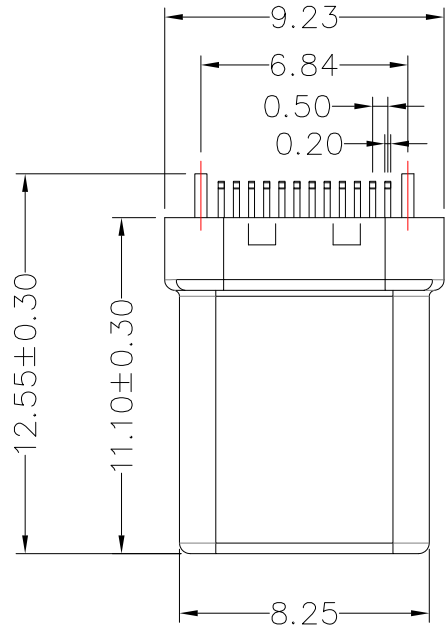




SBC-241PL26-31x-S271

鍍層厚度 :

| |
|-------------|
| Blank : 1u" |
| 2 : 15u" |
| 3 : 30u" |



PCB LATOUT

SPECIFICATIONS

Electrical:

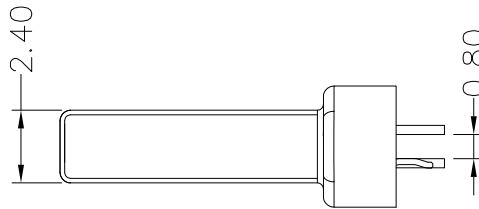
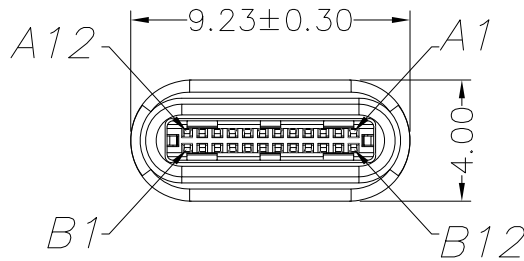
- 1.Current Rating: 0.5A
- 2.Contact Resistance: 30 mΩ Max
- 3.Dielectric Withstanding Voltage: 100 V AC
- 5.Insulation Resistance: 100 MΩ Min

Material:

- 1.Housing:LCP
- 2.Contact: Copper Alloy
- 3.Shell: SUS

Finish:

- 1.Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.Shell: Nickel under Plated surface layer



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CONTACT TECHNOLOGY CORP.

TOLERANCE-UNLESS OTHERWISE STATED :

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD. ANGEL'S



UNITS

MM

| | |
|--------------|----------|
| DRAWN BY: | DATE |
| Jack Lu | 06/08/20 |
| CHECKED BY: | DATE |
| Jacky Chen | 06/08/20 |
| APPROVED BY: | DATE |
| Tony Kao | 06/08/20 |

| | | | |
|-----------|--------|----------|----------------------|
| MATL | | TITLE | CONNECTOR |
| FINISH | | MODLE | TYPE C 公頭不帶板 拉伸款 |
| SCALE | 1 : 1 | DWG NO. | SBC-241PL26-31x-S271 |
| SHEET NO. | 1 of 1 | PART NO. | SBC-241PL26-31x-S271 |
| | | SIZE | A4 |
| | | VER | R2 |

| | | | |
|----------|--------------|-------|--------|
| 2 | 更新尺寸 | Jack | 060820 |
| 1 | 更新PCB LAYOUT | Jack | 123019 |
| ITEM NO. | DESCRIPTION | DRAWN | DATE |